



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSC031N06NS3 G	Issued	24. February 2022
MA#	MA005700286		
Package	PG-TDSON-8-1	Weight*	122.21 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.425	3.62	3.62	36210	36210
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		93	
	non noble metal	iron	7439-89-6	0.038	0.03		309	
	non noble metal	copper	7440-50-8	37.762	30.88	30.92	308983	309385
wire	non noble metal	copper	7440-50-8	0.072	0.06	0.06	589	589
encapsulation	organic material	carbon black	1333-86-4	0.080	0.07		652	
	plastics	epoxy resin	-	5.660	4.63		46311	
	inorganic material	silicondioxide	60676-86-0	34.118	27.92	32.62	279168	326131
leadfinish	non noble metal	tin	7440-31-5	1.452	1.19	1.19	11878	11878
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1354	1354
solder	non noble metal	tin	7440-31-5	0.070	0.06		570	
	noble metal	silver	7440-22-4	0.087	0.07		713	
	non noble metal	lead	7439-92-1	3.328	2.72	2.85	27234	28517
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	iron	7439-89-6	0.022	0.02		183	
	noble metal	silver	7440-22-4	1.289	1.06		10551	
	non noble metal	copper	7440-50-8	22.292	18.24	19.33	182400	193189
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	iron	7439-89-6	0.011	0.01		93	
	non noble metal	copper	7440-50-8	11.320	9.26	9.27	92626	92747
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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